

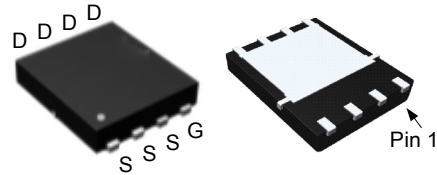
Features

- 40V/120A,
 $R_{DS(ON)} = 2m\Omega$ (typ.) @ $V_{GS}=10V$
 $R_{DS(ON)} = 2.6m\Omega$ (typ.) @ $V_{GS}=4.5V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lower Q_g and Q_{gd} for high-speed switching
- Lower $R_{DS(ON)}$ to Minimize Conduction Losses
- Lead Free and Green Devices Available
(RoHS Compliant)

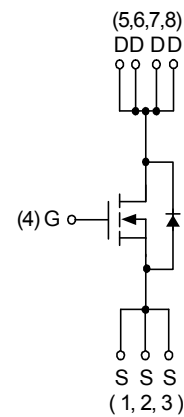
Applications

- Power Management in Desktop Computer or DC/DC Converters.

Pin Description



DFN5x6-8



N-Channel MOSFET

Absolute Maximum Ratings (T_A = 25°C Unless Otherwise Noted)

Symbol	Parameter		Rating	Unit
Common Ratings				
V _{DSS}	Drain-Source Voltage		40	V
V _{GSS}	Gate-Source Voltage		±20	
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to 150	
I _S	Diode Continuous Forward Current	T _C =25°C	120	A
I _D	Continuous Drain Current	T _C =25°C	120	
		T _C =100°C	48	
I _{DM} ^b	Pulsed Drain Current	T _C =25°C	360	
P _D	Maximum Power Dissipation	T _C =25°C	78.1	W
		T _C =100°C	31.3	
R _{θJC}	Thermal Resistance-Junction to Case	Steady State	1.6	°C/W
I _D ^c	Continuous Drain Current	T _A =25°C	21	A
		T _A =70°C	16.6	
P _D ^c	Maximum Power Dissipation	T _A =25°C	2.1	W
		T _A =70°C	1.3	
R _{θJA} ^c	Thermal Resistance-Junction to Ambient	t ≤ 10s	20.5	°C/W
		Steady State	60	
I _{AS} ^d	Avalanche Current, Single pulse	L=0.1mH	45	A
E _{AS} ^d	Avalanche Energy, Single pulse	L=0.1mH	101.3	mJ

Note a : Max. continue current is limited by bonding wire

Note b : Pulse width is limited by max. junction temperature.

Note c : R_{θJA} steady state t=999s

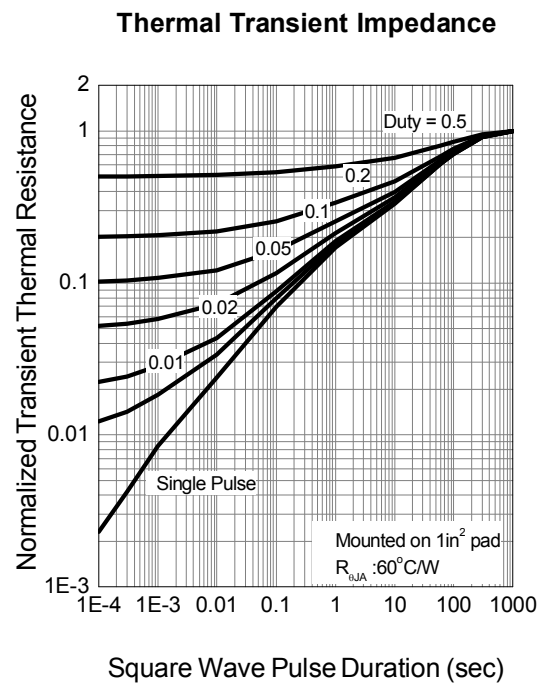
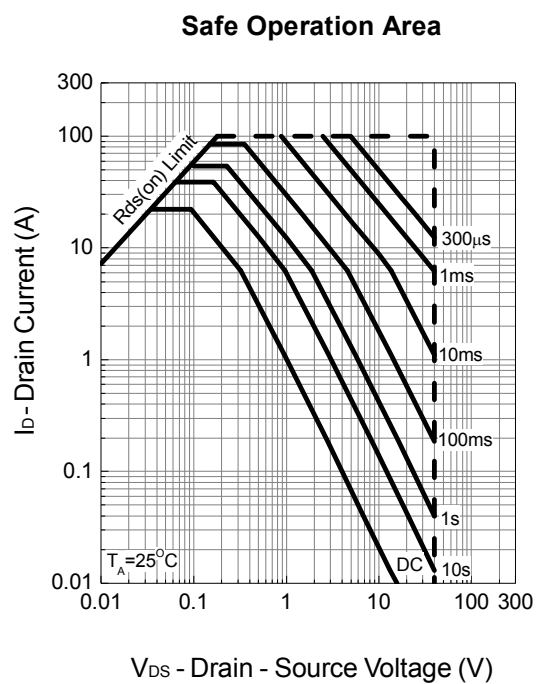
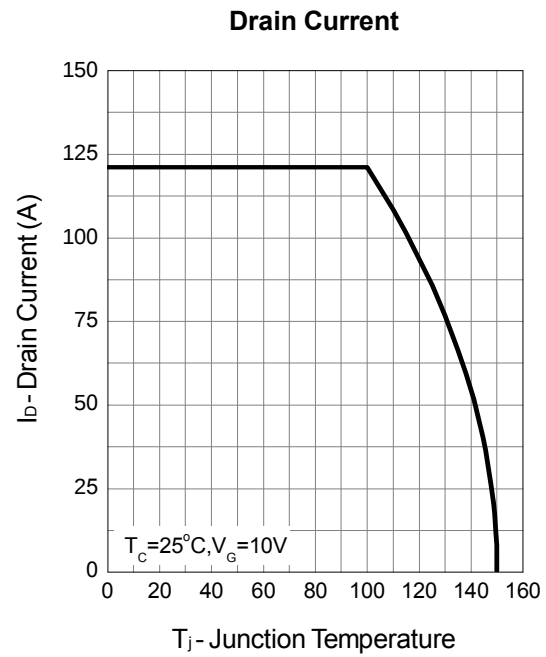
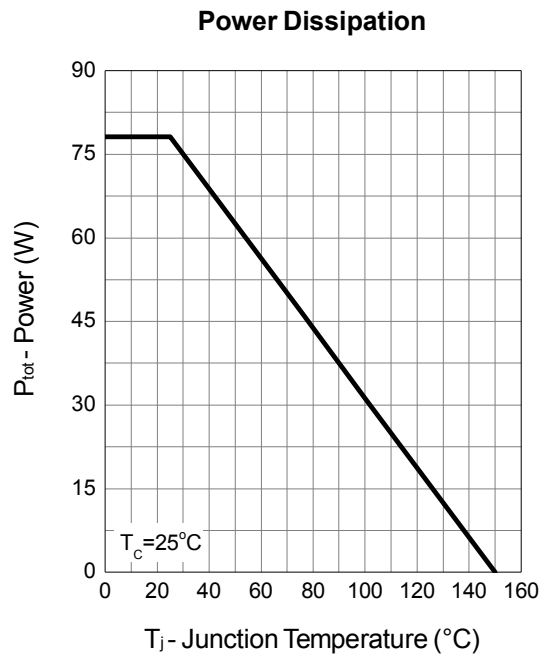
Note d : UIS tested and pulse width limited by maximum junction temperature 175°C (initial temperature T_J=25°C).

Electrical Characteristics (T_A = 25°C unless otherwise noted)

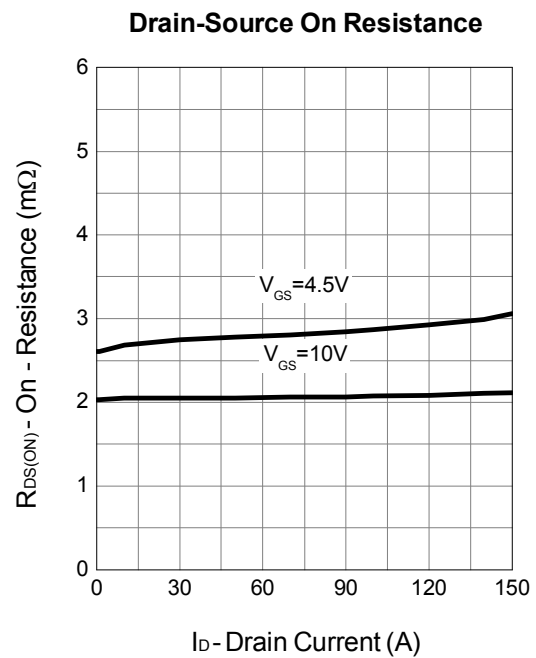
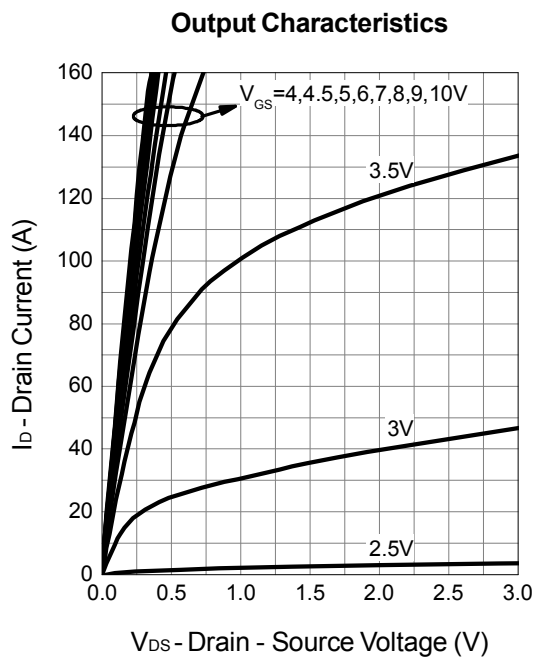
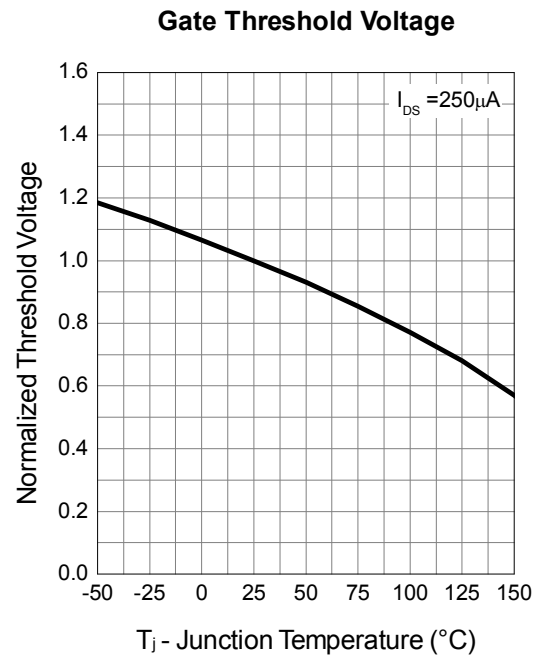
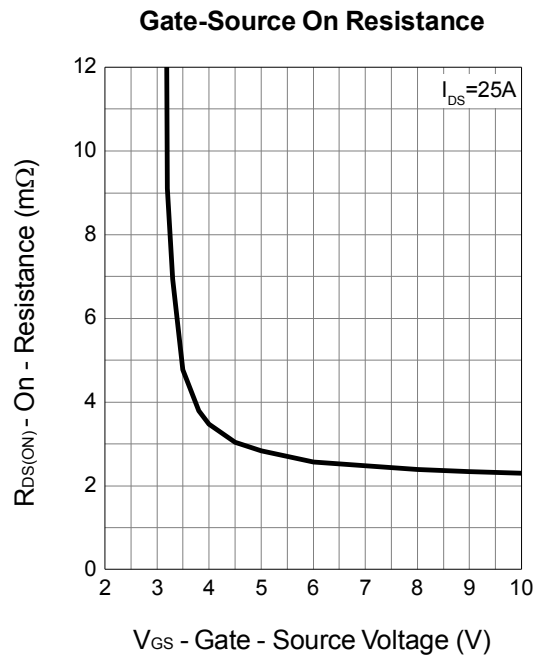
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =32V, V _{GS} =0V T _J =85°C	-	-	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1.4	1.7	2.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^e	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =25A T _J =100°C	-	2 3.2	2.7 -	mΩ
Gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =20A	-	50	-	S
Diode Characteristics						
V _{SD} ^e	Diode Forward Voltage	I _{SD} =20A, V _{GS} =0V	-	0.8	1.1	V
t _{rr}	Reverse Recovery Time	I _{SD} =5A, dI _{SD} /dt=100A/μs V _{dd} =25V	-	38	-	ns
t _a	Charge Time		-	23	-	
t _b	Discharge Time		-	15.5	-	
Q _{rr}	Reverse Recovery Charge		-	30	-	nC
Dynamic Characteristics						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	0.9	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, Frequency=1.0MHz	-	6080	-	pF
C _{oss}	Output Capacitance		-	600	-	
C _{rss}	Reverse Transfer Capacitance		-	496	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =20V, R _L =20Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	17	-	ns
t _r	Turn-on Rise Time		-	9	-	
t _{d(OFF)}	Turn-off Delay Time		-	39	-	
t _f	Turn-off Fall Time		-	34.5	-	
Gate Charge Characteristics						
Q _g	Total Gate Charge	V _{DS} =20V, V _{GS} =10V, I _{DS} =25A	-	45	58.5	nC
Q _g	Total Gate Charge	V _{DS} =20V, V _{GS} =4.5V, I _{DS} =25A	-	21		
Q _{gth}	Threshold Gate Charge		-	5	-	
Q _{gs}	Gate-Source Charge		-	8.8	-	
Q _{gd}	Gate-Drain Charge		-	5.5	-	

Note e : Pulse test ; pulse width≤300μs, duty cycle≤2%.

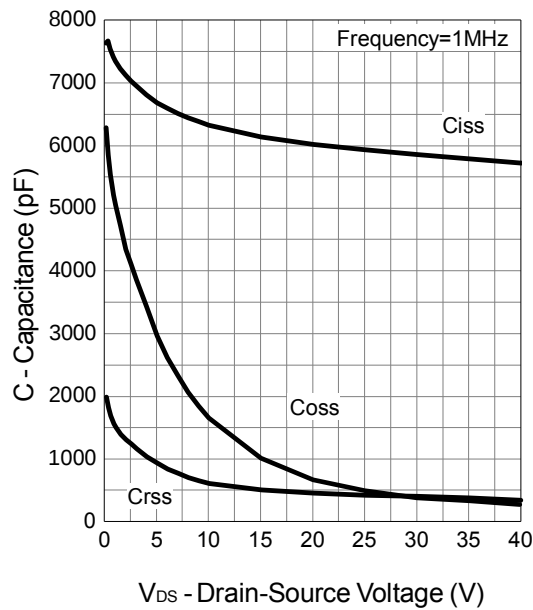
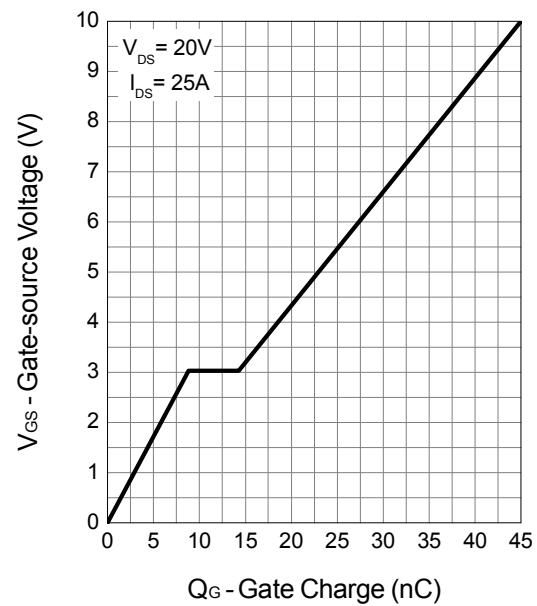
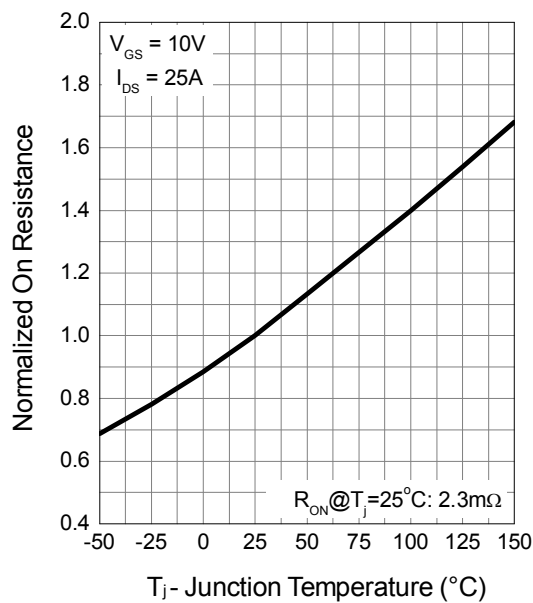
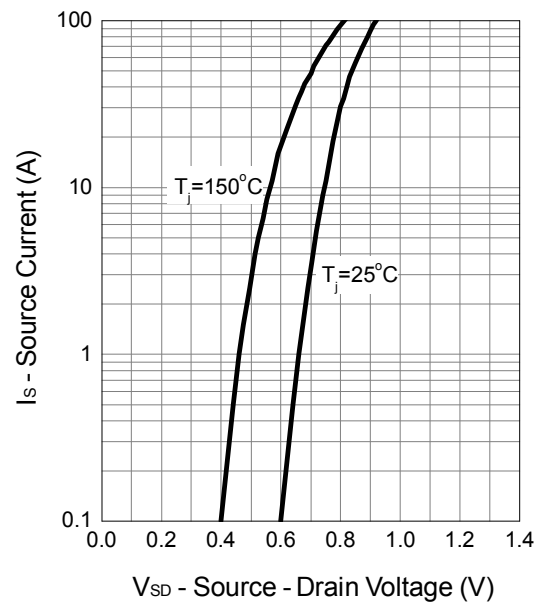
Typical Operating Characteristics



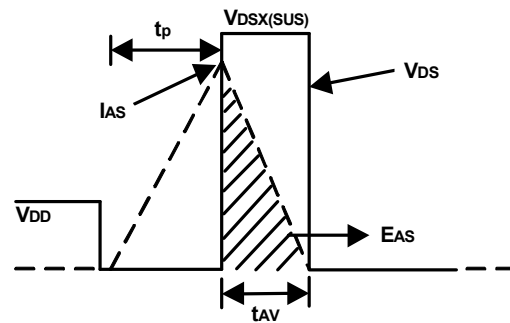
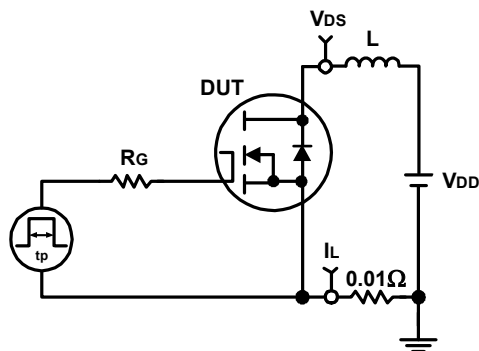
Typical Operating Characteristics (Cont.)



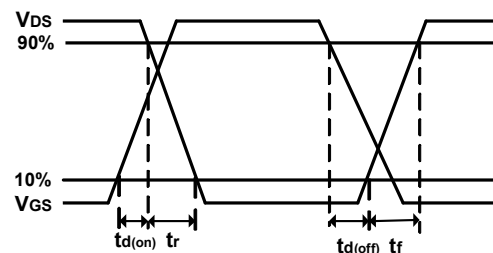
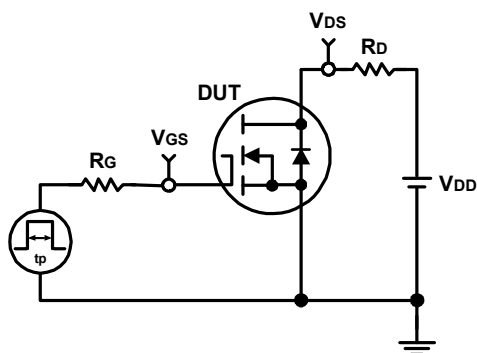
Typical Operating Characteristics (Cont.)

Capacitance

Gate Charge

Drain-Source On Resistance

Source-Drain Diode Forward


Avalanche Test Circuit and Waveforms

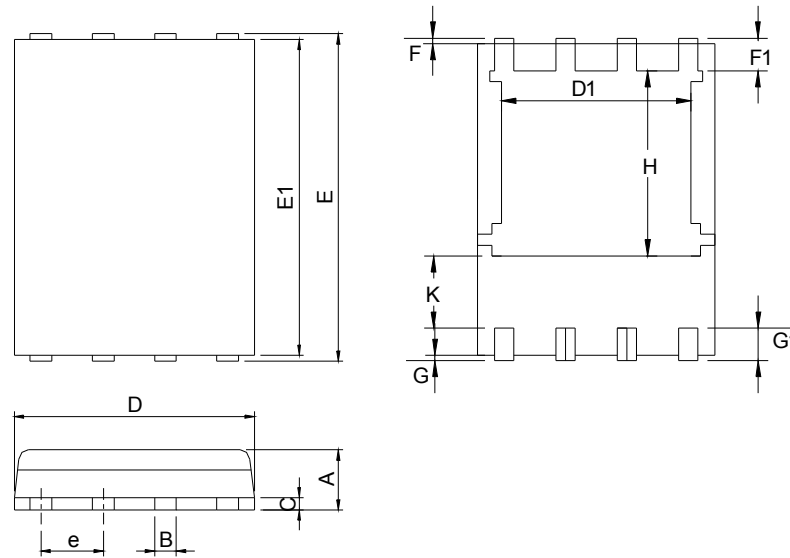


Switching Time Test Circuit and Waveforms



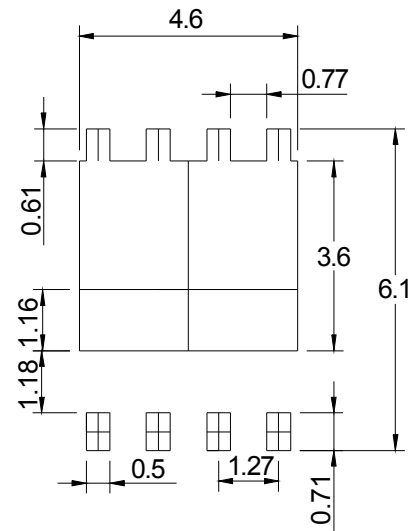
Package Information

DFN5x6-8



SYMBOL	DFN5x6-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.90	1.20	0.035	0.047
B	0.3	0.51	0.012	0.020
C	0.19	0.25	0.007	0.010
D	4.80	5.30	0.189	0.209
D1	4.00	4.40	0.157	0.173
E	5.90	6.20	0.232	0.244
E1	5.50	5.80	0.217	0.228
e	1.27 BSC		0.050 BSC	
F	0.05	0.30	0.002	0.012
F1	0.35	0.75	0.014	0.030
G	0.05	0.30	0.002	0.012
G1	0.35	0.75	0.014	0.030
H	3.34	3.9	0.131	0.154
K	0.762	-	0.03	-

RECOMMENDED LAND PATTERN



UNIT: mm

Note : 1.Dimension D, D1,D2 and E1 do not include mold flash or protrusions.
Mold flash or protrusions shall not exceed 10 mil.